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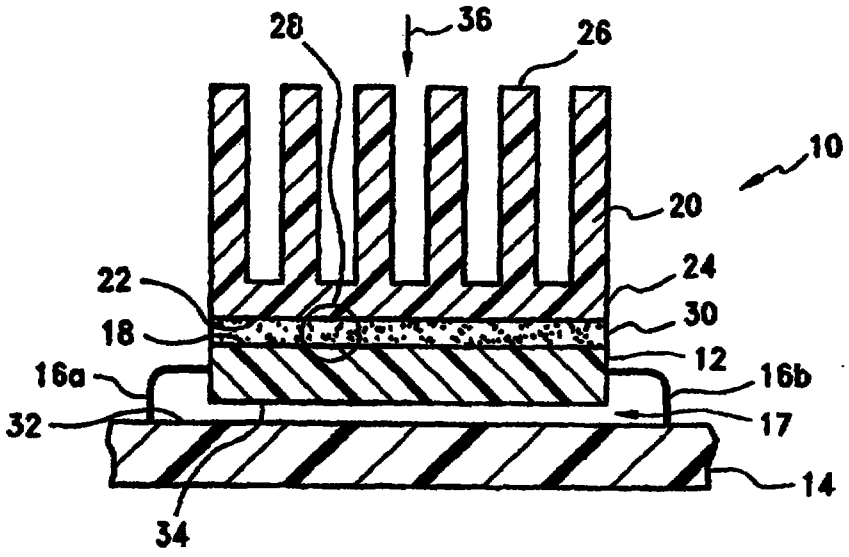
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(54) Title: CONFORMAL THERMAL INTERFACE MATERIAL FOR ELECTRONIC COMPONENTS



(57) Abstract

A thermally-conductive interface (30) for conductively cooling a heat-generating electronic component (12) having an associated thermal dissipation member such as a heat sink (20). The interface is formed as a self-supporting layer of a thermally-conductive material which is form-stable at normal room temperature in a first phase and substantially conformable in a second phase to the interface surfaces of the electronic component and thermal dissipation member. The material has a transition temperature from the first phase to the second phase which is within the operating temperature range of the electronic component.